

Supplementary Material

Interdiffusion and Intermetallic Compounds at Al/Cu Interfaces in Al-50vol.%Cu Composite Prepared by Solid-State Sintering

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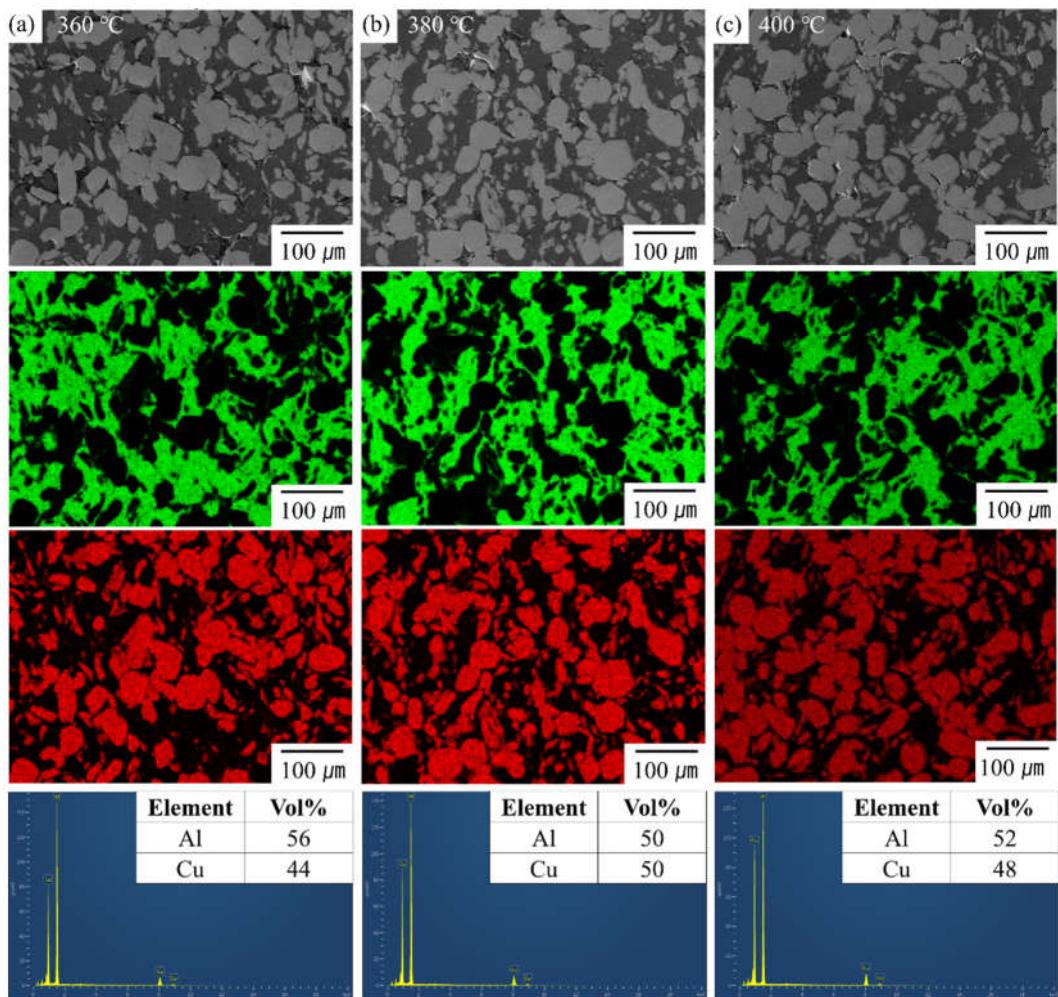


Figure S1. FE-SEM image and EDS mapping result with Al and Cu element of A-50vol.%Cu composites sintered at (a) 360 °C, (b) 380 °C and (c) 400 °C.